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J. White

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Form PTO-1449 LIST OF PATENTS AND PUBLICATIONS FOR INFORMATION DISCLOSURE STATEMENT (Use Several Sheets if Necessary)	APPLICANT: Son K. Quan	
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U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	ISSUE DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
HVN	AA	5,776,798	Jul.7,'98	Quan et al.	438	112	Sep.4,'96
HVN	AB	5,641,714	Jun.24,'97	Yamanaka	438	14	Jan.16,'96
HVN	AC	5,612,513	Mar.18,'97	Tuttle et al.	174	260	Sep.19,'95
HVN	AD	5,604,160	Feb.18,'97	Warfield	437	209	Jul.29,'96
HVN	AE	5,491,111	Feb.13,'96	Tai	437	209	Oct.26,'94
HVN	AF	5,462,636	Oct.31,'95	Chen et al.	216	17	Dec.28,'93
HVN	AG	5,188,984	Feb.23,'93	Nishiguchi	437	211	Feb.4,'91
HVN	AH	5,061,657	Oct.29,'91	Queen et al	437	219	Jul.18,'90
HVN	AI	4,961,821	Oct.9,'90	Drake et al.	156	647	Nov.22,'89
HVN	AJ	5,690,773	Nov.25,'73	Fidalgo et al.	156	267	Feb.22,'95

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	PUBLICATION DATE (#43)	COUNTRY	CLASS	SUBCLASS
HVN	AK	6-132423 (w/Eng.Translation)	May 13,'94	Japan	H01L	23/28
	AL					
	AM					
	AN					
	AO					

OTHER INFORMATION (Including Author, Title, Date, Pertinent Pages, Etc.)

HVN	AP	John R. Arnold et al., "Materials - Stressed-Out"- Microelectronic Encapsulation Finds Cure in Aerobic Adhesives, Advanced Packaging Jan-Feb 1996, pgs. 31-34.
	AR	
	AS	
	AT	
	AU	
	AV	

EXAMINER DATE CONSIDERED

HVN V Ngai 022402

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.